

Features

- 0.3 INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- I.C. COMPATIBLE.
- MECHANICALLY RUGGED.
- GRAY FACE, WHITE SEGMENT.
- PACKAGE : 1100PCS / REEL.

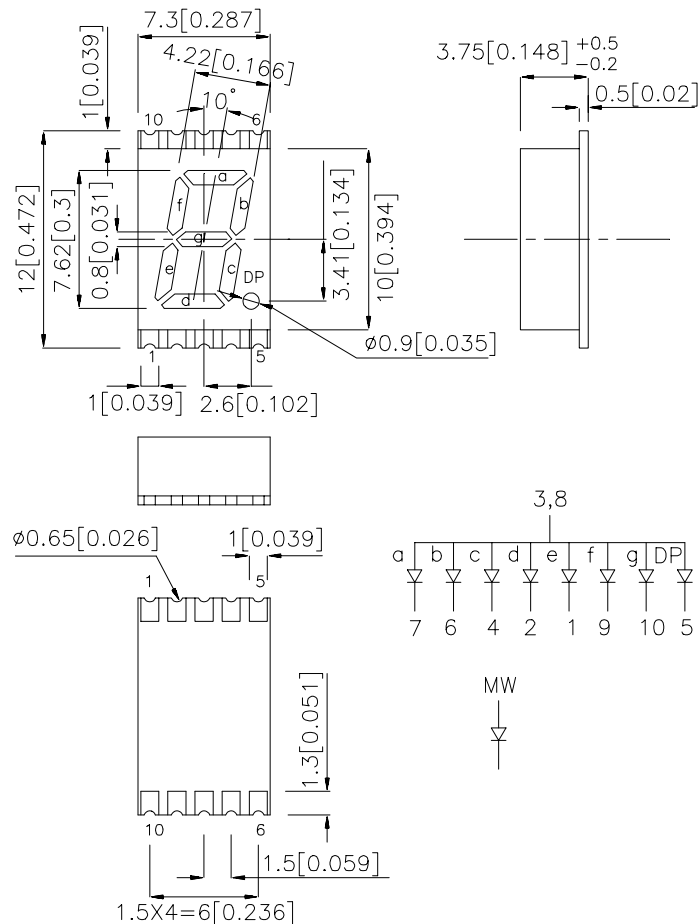
Description

The source color devices are made with GaN on SiC Light Emitting Diode.

Static electricity and surge damage the LEDs. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions& Internal Circuit Diagram



Notes:

1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
2. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (ucd) @ 20 mA		Description
			Min.	Typ.	
KPSA03-112	WHITE (GaN)	WHITE DIFFUSED	2600	13500	Common Anode,Rt. Hand Decimal

Electrical / Optical Characteristics at T_A=25°C

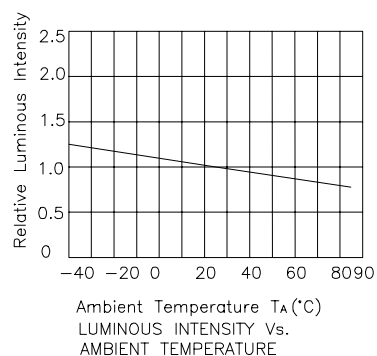
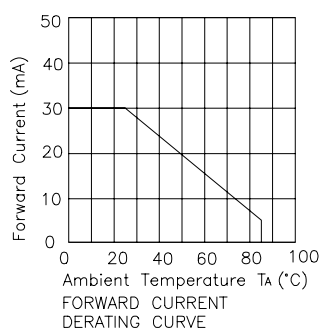
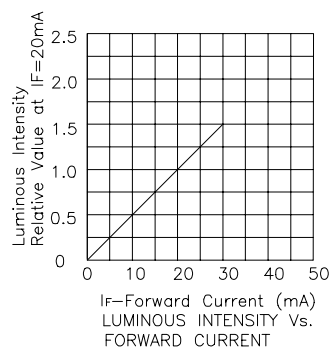
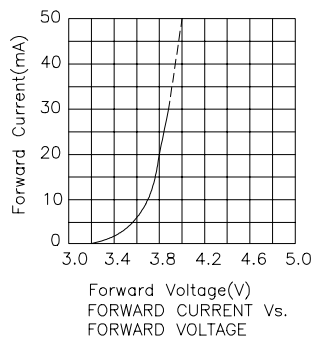
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
V _F	Forward Voltage	White	3.8	4.5	V	I _F =20mA
I _R	Reverse Current	White	-	10	uA	V _R = 5V
X	Chromaticity Coordinates	White	0.33	-	-	-
Y			0.34	-	-	-
C	Capacitance	White	100	-	pF	V _F =0V, f =1MHz

Absolute Maximum Ratings at T_A=25°C

Parameter	White	Units
Power dissipation	105	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	

Note:

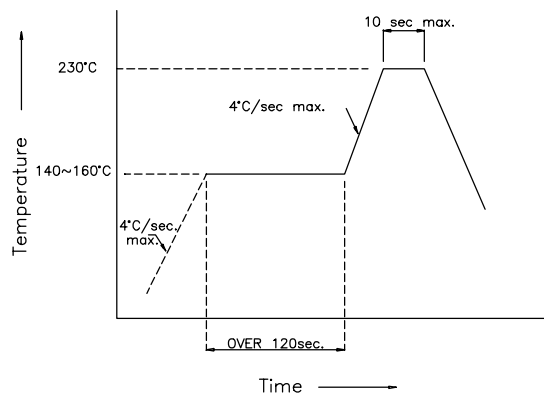
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



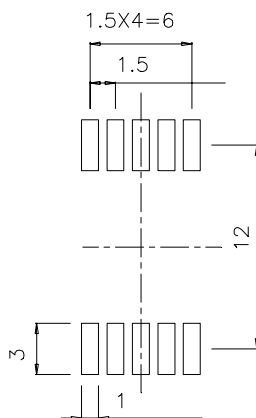
KPSA03-112

SMT Reflow Soldering Instruction

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern (Units : mm)



Tape Specification (Units : mm)

